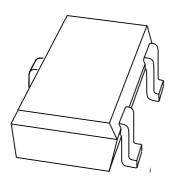
### **DISCRETE SEMICONDUCTORS**

# DATA SHEET



# **BF820W**NPN high-voltage transistor

Product specification Supersedes data of 1997 Sep 03 2003 Sep 09





# **NPN** high-voltage transistor

**BF820W** 

#### **FEATURES**

- Low current (max. 50 mA)
- High voltage (max. 300 V).

#### **APPLICATIONS**

• Telephony and professional communication equipment.

#### **DESCRIPTION**

NPN high-voltage transistor in a SOT323 plastic package.

#### **MARKING**

TYPE NUMBER	MARKING CODE(1)	
BF820W	1V*	

#### **Notes**

\* = p : made in Hong Kong.
 \* = t : made in Malaysia.

\* = W : made in China.

#### **PINNING**

PIN	DESCRIPTION	
1	base	
2	emitter	
3	collector	

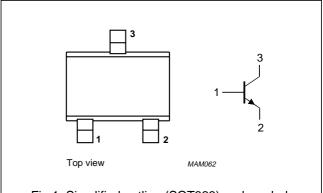


Fig.1 Simplified outline (SOT323) and symbol.

#### **QUICK REFERENCE DATA**

SYMBOL	PARAMETER	PARAMETER CONDITIONS		MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	300	٧
V <sub>CEO</sub>	collector-emitter voltage	open base	_	300	V
I <sub>CM</sub>	peak collector current		_	100	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	_	200	mW
h <sub>FE</sub>	DC current gain	I <sub>C</sub> = 25 mA; V <sub>CE</sub> = 20 V	50	_	
C <sub>re</sub>	feedback capacitance	$I_C = i_c = 0$ ; $V_{CB} = 30 \text{ V}$ ; $f = 1 \text{ MHz}$	_	1.6	pF
f <sub>T</sub>	transition frequency	I <sub>C</sub> = 10 mA; V <sub>CE</sub> = 10 V; f = 100 MHz	60	_	MHz

2003 Sep 09 2

Philips Semiconductors Product specification

# NPN high-voltage transistor

**BF820W** 

#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS		MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	300	V
V <sub>CEO</sub>	collector-emitter voltage	open base	_	300	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	5	V
I <sub>C</sub>	collector current (DC)		_	50	mA
I <sub>CM</sub>	peak collector current		_	100	mA
I <sub>BM</sub>	peak base current		_	50	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	_	200	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	625	K/W

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

#### **CHARACTERISTICS**

 $T_j$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I <sub>CBO</sub>	collector cut-off current	I <sub>E</sub> = 0; V <sub>CB</sub> = 200 V	_	10	nA
		I <sub>E</sub> = 0; V <sub>CB</sub> = 200 V; T <sub>j</sub> = 150 °C	_	10	μΑ
I <sub>EBO</sub>	emitter cut-off current	I <sub>C</sub> = 0; V <sub>EB</sub> = 5 V	_	50	nA
h <sub>FE</sub>	DC current gain	I <sub>C</sub> = 25 mA; V <sub>CE</sub> = 20 V	50	_	
V <sub>CEsat</sub>	collector-emitter saturation voltage	I <sub>C</sub> = 30 mA; I <sub>B</sub> = 5 mA; note 1	_	600	mV
C <sub>re</sub>	feedback capacitance	$I_C = i_c = 0$ ; $V_{CB} = 30 \text{ V}$ ; $f = 1 \text{ MHz}$	_	1.6	pF
f <sub>T</sub>	transition frequency	I <sub>C</sub> = 10 mA; V <sub>CE</sub> = 10 V; f = 100 MHz	60	_	MHz

#### Note

1. Pulse test:  $t_p \le 300 \ \mu s; \ \delta \le 0.02.$ 

2003 Sep 09 3

Philips Semiconductors Product specification

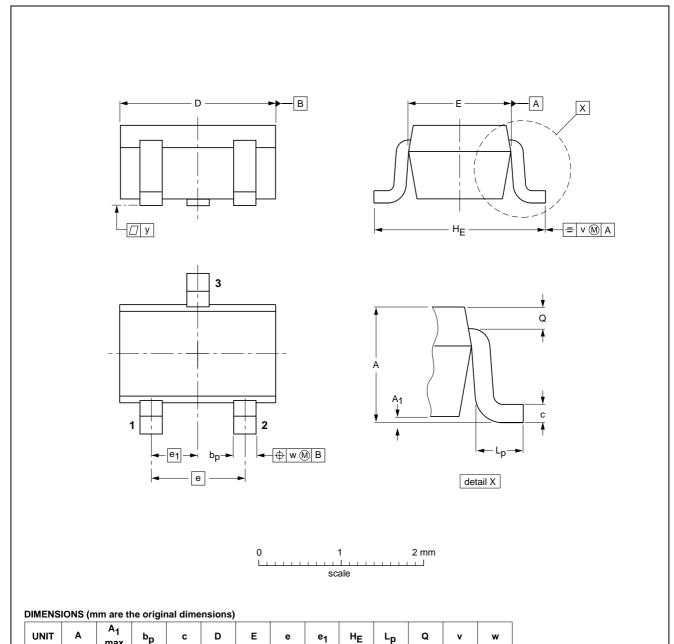
# NPN high-voltage transistor

**BF820W** 

#### **PACKAGE OUTLINE**

Plastic surface mounted package; 3 leads

**SOT323** 



OUTLINE	INE REFERENCES		EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	1330E DATE
SOT323			SC-70			97-02-28

0.65

0.45 0.15 0.23 0.13

0.2

2003 Sep 09 4

0.4 0.3 0.25 0.10 2.2 1.8 1.35 1.15

1.3

1.1 0.8

mm

0.1

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#### NPN high-voltage transistor

**BF820W** 

#### **DATA SHEET STATUS**

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS(2)(3)	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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#### **DEFINITIONS**

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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2003 Sep 09 5

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